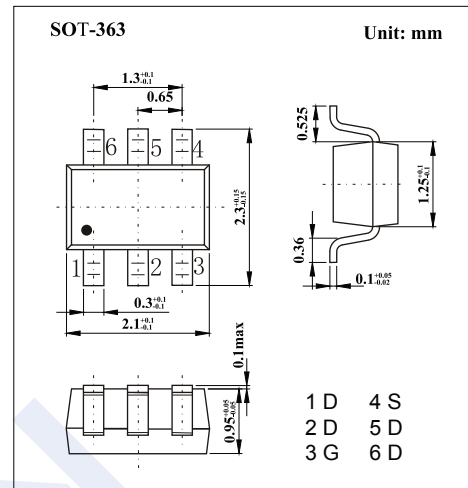
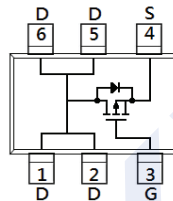


P-Channel MOSFET

2KJ6039

■ Features

- $V_{DS} (V) = -20V$
- $I_D = -2.5A$
- $R_{DS(ON)} < 85m\Omega @ V_{GS} = -4.5V, I_D = -2.5A$
- $R_{DS(ON)} < 115m\Omega @ V_{GS} = -2.5V, I_D = -1.8A$
- $R_{DS(ON)} < 150m\Omega @ V_{GS} = -1.8V, I_D = -1.3A$
- $R_{DS(ON)} < 250m\Omega @ V_{GS} = -1.5V, I_D = -0.5A$
- Advanced Trench Process Technology

■ Absolute Maximum Ratings ($T_A = 25^\circ C$ Unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 12	
Continuous Drain Current	I_D	-2.5	A
Pulsed Drain Current (Note 1)	I_{DM}	-10	
Power Dissipation	P_D	750	mW
Thermal Resistance, Junction- to-Ambient (Note 2)	$R_{\theta JA}$	167	$^\circ C/W$
Junction Temperature	T_J	150	$^\circ C$
Junction Storage Temperature Range	T_{stg}	-55 to 150	

Notes:

1. The maximum current rating is package limited.
2. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins mounted on a 1 inch FR-4 with 2oz. square pad of copper.

P-Channel MOSFET

2KJ6039

■ Electrical Characteristics ($T_A = 25^\circ\text{C}$ Unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BVDSS	$I_D = -250\mu\text{A}$, $V_{GS} = 0\text{V}$	-20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -20\text{V}$, $V_{GS} = 0\text{V}$			-1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{DS} = 0\text{V}$, $V_{GS} = \pm 12\text{V}$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = -250\mu\text{A}$	-0.4	-0.7	-1.0	V
Static Drain-Source On-Resistance (Note 3)	$R_{DS(on)}$	$V_{GS} = -4.5\text{V}$, $I_D = -2.5\text{A}$			85	m Ω
		$V_{GS} = -2.5\text{V}$, $I_D = -1.8\text{A}$			115	
		$V_{GS} = -1.8\text{V}$, $I_D = -1.3\text{A}$			150	
		$V_{GS} = -1.5\text{V}$, $I_D = -0.5\text{A}$			250	
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{GS} = 0\text{V}$, $V_{DS} = -10\text{V}$, $f = 1\text{MHz}$		522		pF
Output Capacitance	C_{oss}			55		
Reverse Transfer Capacitance	C_{rss}			40		
Total Gate Charge	Q_g	$V_{DS} = -10\text{V}$, $I_D = -2.2\text{A}$, $V_{GS} = -4.5\text{V}$ (Note 3,4)		7		nC
Gate Source Charge	Q_{gs}			1		
Gate Drain Charge	Q_{gd}			1.8		
Switching Characteristics						
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -10\text{V}$, $I_D = -2.2\text{A}$, $V_{GS} = -4.5\text{V}$, $R_G = 6\Omega$ (Note 3,4)		10		ns
Turn-On Rise Time	t_r			4		
Turn-Off Delay Time	$t_{d(off)}$			34		
Turn-Off Fall Time	t_f			5		
Drain-Source Diode Characteristics						
Maximum Body-Diode Continuous Current	I_S				-1.0	A
Diode Forward Voltage	V_{SD}	$I_{SD} = -1.0\text{A}$, $V_{GS} = 0\text{V}$			-1.2	V

Notes

- Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$
- Essentially independent of operating temperature typical characteristics.
- Guaranteed by design, not subject to production testing

■ Marking

Marking	JAU
---------	-----

P-Channel MOSFET

2KJ6039

Typical Characteristics

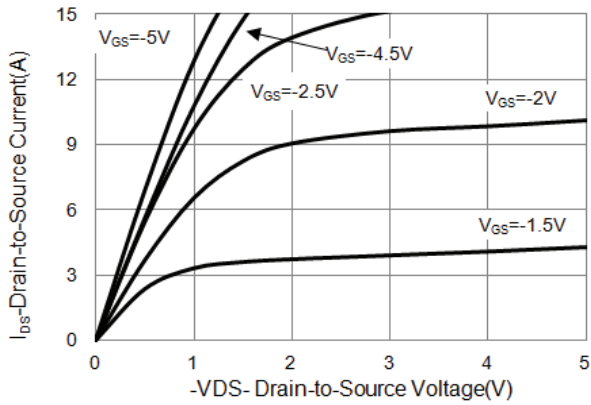


Fig.1 On Region Characteristics

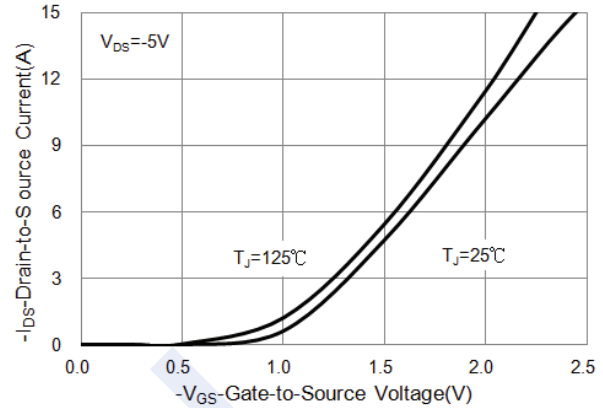


Fig.2 Transfer Characteristics

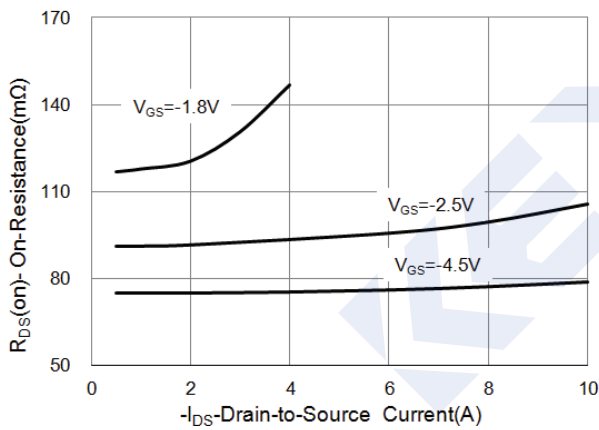


Fig.3 On-Resistance vs. Drain Current

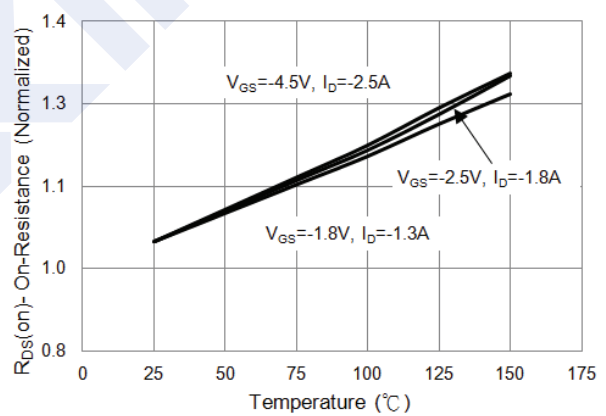


Fig.4 On-Resistance vs. Junction temperature

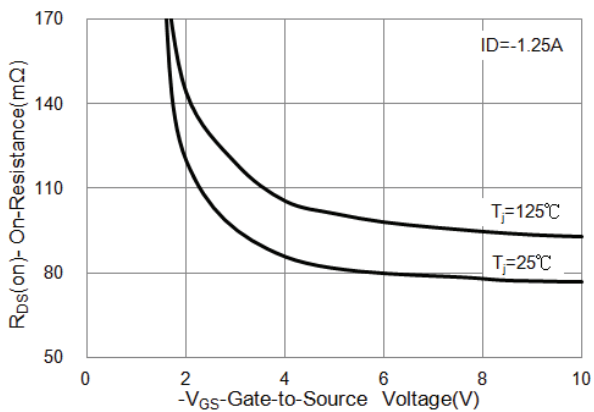


Fig.5 On-Resistance Variation with V_{GS} .

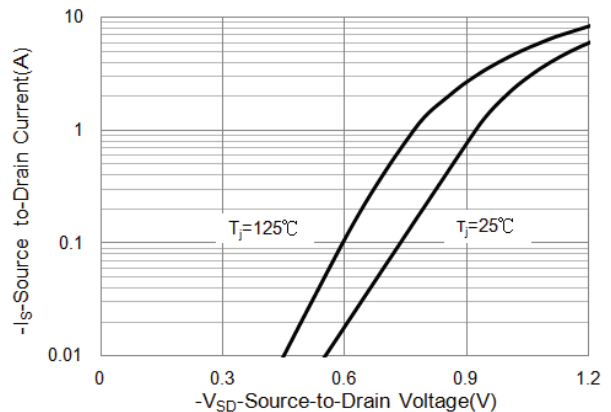


Fig.6 Body Diode Characteristics

P-Channel MOSFET

2KJ6039

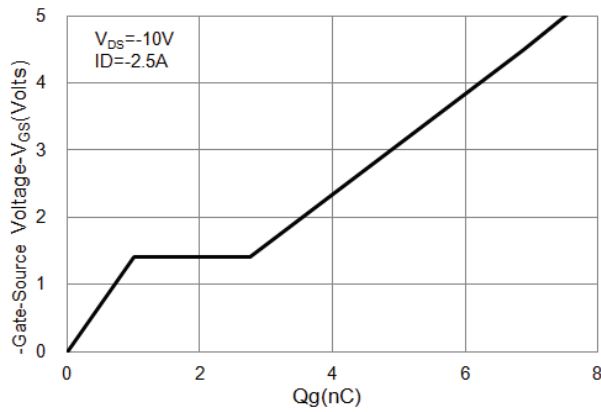


Fig.7 Gate-Charge Characteristics

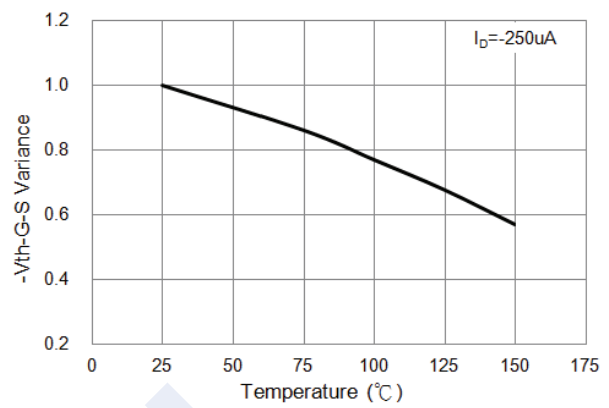


Fig.8 Threshold Voltage Variation with Temperature

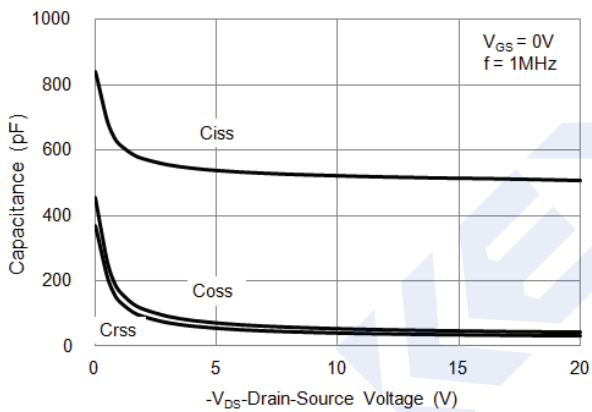


Fig.9 Capacitance vs. Drain-Source Voltage.